### Features

- Supply Voltage 5V (Typically)
- Very Low Power Consumption: 150 mW (Typically) for -1 dBm Output Level
- Very Good Sideband Suppression by Means of Duty Cycle Regeneration of the LO Input Signal
- Phase Control Loop for Precise 90° Phase Shifting
- Power-down Mode
- Low LO Input Level: -10 dBm (Typically)
- 50- $\Omega \, \text{Single-ended LO}$  and RF Port
- LO Frequency from 100 MHz to 1 GHz
- SO16 Package

### **Benefits**

- No External Components Required for Phase Shifting
- Adjustment Free, Hence Saves Manufacturing Time
- Only Three External Components Necessary, this Results in Cost and Board Space Saving

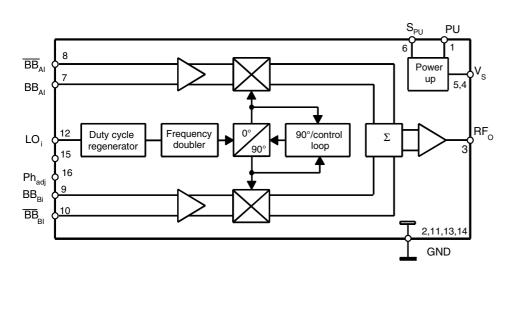
Electrostatic sensitive device. Observe precautions for handling.



### 1. Description

The U2790B is a 1000-MHz quadrature modulator using Atmel<sup>®</sup>'s advanced UHF process. It features a frequency range from 100 MHz up to 1000 MHz, low current consumption, and single-ended RF and LO ports. Adjustment-free application makes the direct converter suitable for all digital radio systems up to 1000 MHz, e.g., GSM, ADC, JDC.

Figure 1-1. Block Diagram





1000-MHz Quadrature Modulator

# U2790B

4583D-CELL-07/06





# 2. Pin Configuration

Figure 2-1. Pinning SO16

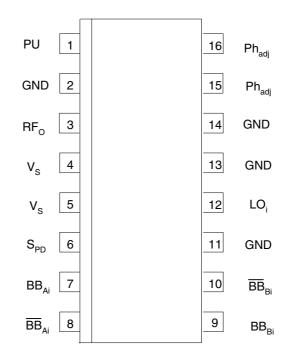


Table 2-1.	Pin Description
------------	-----------------

Pin	Symbol	Function
1	PU	Power-up input
2, 11, 13, 14	GND	Ground
3	$RF_{o}$	RF output
4, 5	Vs	Supply voltage
6	S <sub>PU</sub>	Settling time power-up
7	BB <sub>Ai</sub>	Baseband input A
8	BB <sub>Ai</sub>	Baseband input A inverse
9	BB <sub>Bi</sub>	Baseband input B
10	BB <sub>Bi</sub>	Baseband input B inverse
12	LO <sub>i</sub>	LO input
15, 16	Ph <sub>adj</sub>	Phase adjustment (not necessary for regular applications)

## 3. Absolute Maximum Ratings

Parameters	Symbol	Value	Unit
Supply voltage	V <sub>S</sub>	6	V
Input voltage	V <sub>i</sub>	0 to V <sub>S</sub>	V
Junction temperature	Τ <sub>j</sub>	125	°C
Storage temperature range	T <sub>Stg</sub>	–55 to +125	°C

### 4. Operating Range

Parameters	Symbol	Value	Unit
Supply voltage range	V <sub>S</sub>	4.5 to 5.5	V
Ambient temperature range	T <sub>amb</sub>	-40 to +85	°C

### 5. Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient SO16	R <sub>thJA</sub>	110	K/W

## 6. Electrical Characteristics

Test conditions (unless otherwise specified):  $V_S = 5V$ ,  $T_{amb} = 25^{\circ}C$ , referred to test circuit, system impedance  $Z_O = 50\Omega$ ,  $f_{LO} = 900$  MHz,  $P_{LO} = -10$  dBm,  $V_{BBi} = 1$   $V_{pp}$  differential.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
1.1	Supply voltage range		4, 5	Vs	4.5		5.5	V	А
1.2	Supply current		4, 5	۱ <sub>s</sub>	24	30	37	mA	А
2	Baseband Inputs								
2.1	Input-voltage range (differential)		7-8, 9-10	V <sub>BBi</sub>		1000	1500	mV <sub>pp</sub>	D
2.2	Input impedance (single ended)			Z <sub>BBi</sub>		3.2		kΩ	D
2.3	Input-frequency range <sup>(5)</sup>			f <sub>BBi</sub>	0		250	MHz	D
2.4	Internal bias voltage			V <sub>BBb</sub>	2.35	2.5	2.65	V	A
2.5	Temperature coefficient			TC <sub>BB</sub>		0.1	<1	mV/°C	D

\*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Notes: 1. The required LO level is a function of the LO frequency.

2. In reference to an RF output level  $\leq -1$  dBm and I/Q input level of 400 mV<sub>pp</sub> differential.

- 3. Sideband suppression is tested without connection at pins 15 and 16. For higher requirements a potentiometer can be connected at these pins.
- 4. For  $T_{amb} = -30^{\circ}C$  to  $+85^{\circ}C$  and  $V_{S} = 4.5V$  to 5.5V.
- 5. By low impedance signal source.



R

## 6. Electrical Characteristics (Continued)

Test conditions (unless otherwise specified):  $V_S = 5V$ ,  $T_{amb} = 25^{\circ}C$ , referred to test circuit, system impedance  $Z_O = 50\Omega$ ,  $f_{LO} = 900$  MHz,  $P_{LO} = -10$  dBm,  $V_{BBi} = 1$   $V_{pp}$  differential.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
3	LO Input								
3.1	Frequency range		12	f <sub>LOi</sub>	50		1000	MHz	D
3.2	Input level <sup>(1)</sup>			P <sub>LOi</sub>	-12	-10	-5	dBm	D
3.3	Input impedance			Z <sub>iLO</sub>		50		Ω	D
3.4	Voltage standing wave ratio			VSWR <sub>LO</sub>		1.4	2		D
3.5	Duty cycle range			DCR <sub>LO</sub>	0.4		0.6		D
4	RF Output					•			
4.1	Output level		3	P <sub>RFo</sub>	-5	-1	+2	dBm	В
4.2	LO suppression <sup>(2)</sup>	f <sub>LO</sub> = 900 MHz f <sub>LO</sub> = 150 MHz		LO <sub>RFo</sub>	30 32	35 35		dB	В
4.3	Sideband suppression <sup>(2, 3)</sup>	f <sub>LO</sub> = 900 MHz f <sub>LO</sub> = 150 MHz		SBS <sub>RFo</sub>	35 30	40 35		dB	В
4.4	Phase error <sup>(4)</sup>			Pe		<1		deg.	D
4.5	Amplitude error			A <sub>e</sub>		< ±0.25		dB	D
4.6	Noise floor	$V_{BBi} = 2V, \overline{V}_{BBi} = 3V$ $V_{BBi} = \overline{V}_{BBi} = 2.5V$		N <sub>FL</sub>		-132 -144		dBm/Hz	D
4.7	VSWR			VSWR <sub>RF</sub>		1.6	2		D
4.8	3rd-order baseband harmonic suppression			S <sub>BBH</sub>	35	45		dB	D
4.9	RF harmonic suppression			S <sub>RFH</sub>		35		dB	D
5	Power-up Mode					•			
5.1	Supply current	V <sub>PU</sub> ≤0.5V V <sub>PU</sub> = 1V	4, 5	I <sub>PU</sub>		10	1	μΑ	D
5.2	Settling time	$\begin{array}{l} C_{SPU} = 100 \text{ pF} \\ C_{LO} = 100 \text{ pF} \\ C_{RFo} = 1 \text{ nF} \end{array}$	6 to 3	t <sub>sPU</sub>		10		μs	D
6	Switching Voltage								
6.1	Power-on		1	V <sub>PUon</sub>	4			V	D
6.2	Power-up		1	V <sub>PUdown</sub>			1	V	D
		•							

\*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Notes: 1. The required LO level is a function of the LO frequency.

2. In reference to an RF output level  $\leq -1$  dBm and I/Q input level of 400 mV  $_{\rm pp}$  differential.

3. Sideband suppression is tested without connection at pins 15 and 16. For higher requirements a potentiometer can be connected at these pins.

- 4. For  $T_{amb} = -30^{\circ}C$  to  $+85^{\circ}C$  and  $V_{S} = 4.5V$  to 5.5V.
- 5. By low impedance signal source.

### 7. Diagrams

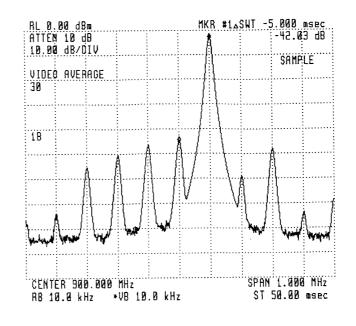


Figure 7-1. Typical Single Sideband Output Spectrum at  $V_S = 4.5V$  and  $V_S = 5.5V$ ,  $f_{LO} = 900$  MHz,  $P_{LO} = -10$  dBm,  $V_{BBI} = 1$   $V_{PP}$  (differential)  $T_{amb} = 25^{\circ}C$ 

Figure 7-2. Typical GMSK Output Spectrum

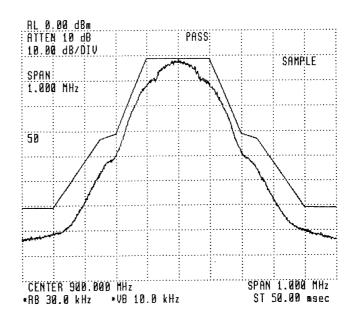






Figure 7-3. Demo Board Layout

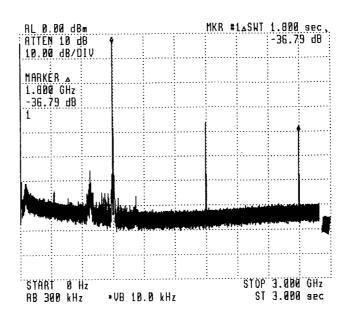


Figure 7-4. OIP3 versus T<sub>amb</sub>, LO = 150 MHz, Level –20 dBm

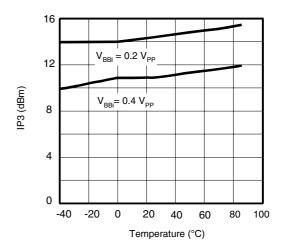


Figure 7-5. OIP3 versus  $T_{amb}$ , LO = 900 MHz, Level –10 dBm

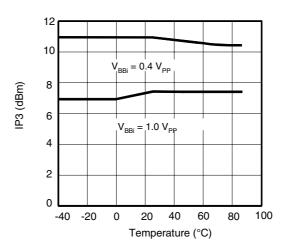


Figure 7-6. Output Power versus T<sub>amb</sub>

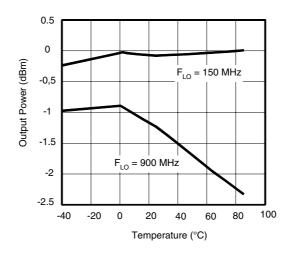
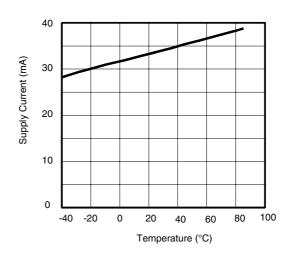
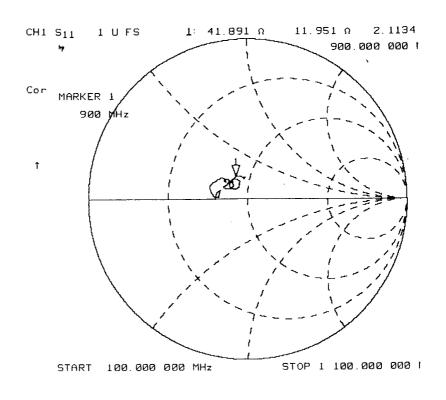


Figure 7-7. Supply Current versus T<sub>amb</sub>









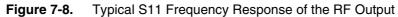
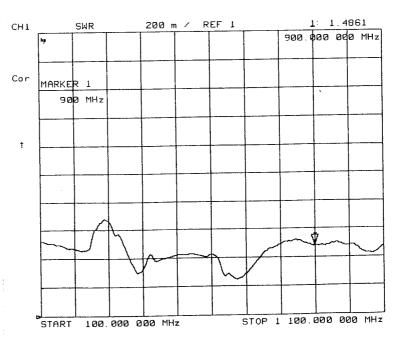


Figure 7-9. Typical VSWR Frequency Response of the RF Output



U2790B

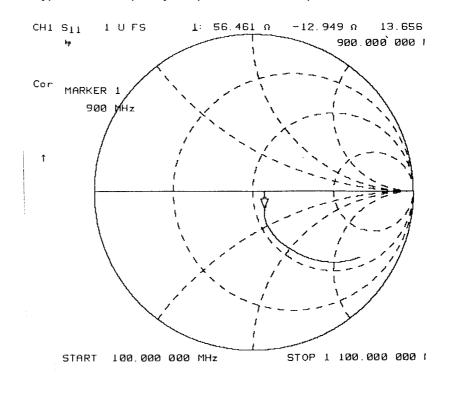


Figure 7-10. Typical S11 Frequency Response of the LO Input

Figure 7-11. Typical VSWR Frequency Response of the LO input

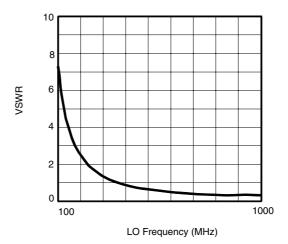






Figure 7-12. Typical Supply Current versus Temperature at  $V_S = 5V$ 

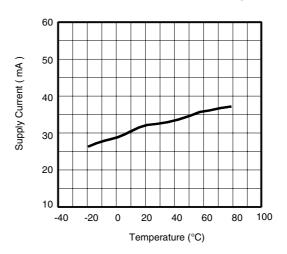


Figure 7-13. Typical Output Power versus LO-Frequency at  $T_{amb} = 25^{\circ}C$ , VBBI = 230 mV<sub>PP</sub> (differential)

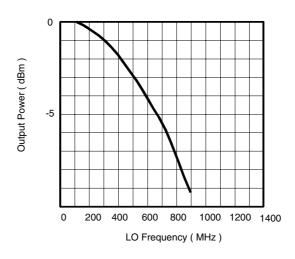
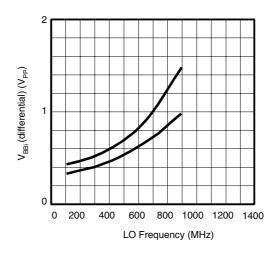
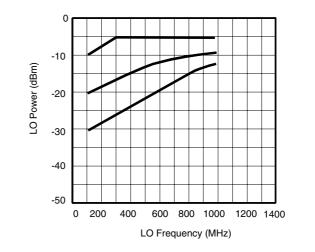


Figure 7-14. Typical required V<sub>BBi</sub> Input Signal (differential) versus LO Frequency for PO = 0 dBm and P<sub>O</sub> = -2 dBm

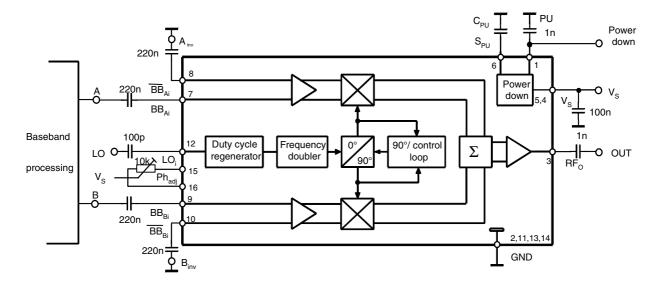


U2790B



**Figure 7-15.** Typical useful LO Power Range versus LO Frequency at  $T_{amb} = 25^{\circ}C$ 

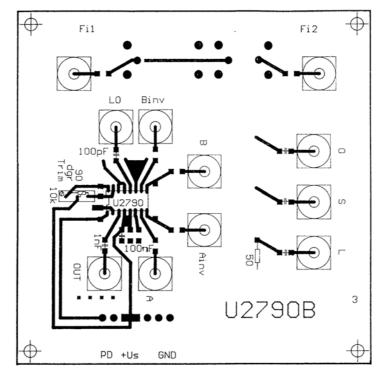
Figure 7-16. Application Circuit







### Figure 7-17. Demo Board Layout



### 8. Application Notes

### 8.1 Noise Floor and Settling Time

In order to reduce noise on the power-up control input and improve the wide-off noise floor of the 900-MHz RF output signal, capacitor  $C_{PU}$  should be connected from pin 6 to ground in the shortest possible way.

The settling time has to be considered for the system under design. For GSM applications, a value of  $C_{PU} = 1$  nF defines a settling time,  $t_{sPU}$ , equal or less than 3 ms. This capacitance does not have any influence on the noise floor within the relevant GSM mask. For mobile applications the mask requirements can be achieved very easily without  $C_{PU}$ .

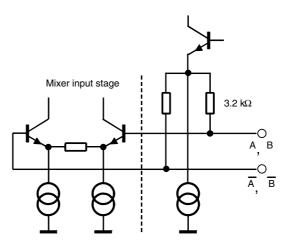
A significant improvement of the wide-off noise floor is obtainable with  $C_{PU}$  greater than 100 nF. Such values are recommended for applications where the settling time is not critical such as in base stations. Coupling capacitors for LO<sub>i</sub> and RF<sub>O</sub> also have a certain impact on the settling time. The values used for the measurements are CLO<sub>i</sub> = 100 pF and C<sub>RFO</sub> = 1 nF.

### 8.2 Baseband Coupling

The U2790B-FP (SO16) has an integrated biasing network which allows AC coupling of the baseband signal at a low count of external components. The bias voltage is  $2.5V \pm 0.15V$ .

Figure 7-17 shows the baseband input circuitry with a resistance of 3.2 k $\Omega$  for each asymmetric input. The internal DC offset between A and A, and B and B is typically < ±1 mV with a maximum of ±3 mV. DC coupling is also possible with an external DC voltage of 2.5 ±0.15V.

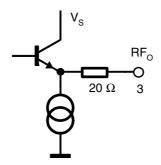
Figure 8-1. Baseband Input Circuitry



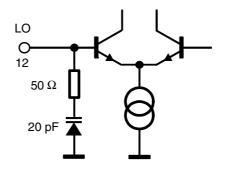




RF Output Circuitry LO Input Circuitry



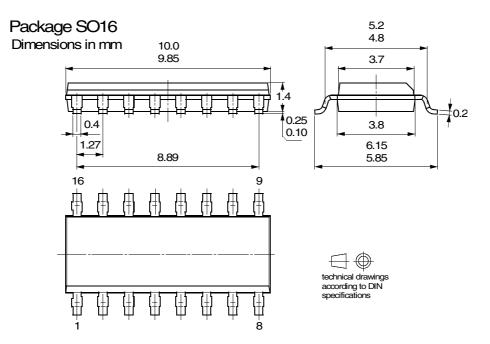




# 9. Ordering Information

Extended Type Number	Package	Remarks
U2790B-NFPH	SO16	Tube, Pb-free
U2790B-NFPG3H	SO16	Taped and reeled, Pb-free

## 10. Package Information



## **11. Revision History**

Please note that the following page numbers referred to in this section refer to the specific revision mentioned, not to this document.

Revision No.	History
4583D-CELL-07/06	<ul> <li>Page 3, Abs. Max.Ratings table: Storage temperature values changed</li> <li>Page 2, Pin Description table: symbol of Pins 8 and 10 changed</li> <li>Put datasheet in a new template</li> </ul>





### **Atmel Corporation**

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 487-2600

#### **Regional Headquarters**

#### Europe

Atmel Sarl Route des Arsenaux 41 Case Postale 80 CH-1705 Fribourg Switzerland Tel: (41) 26-426-5555 Fax: (41) 26-426-5500

#### Asia

Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimshatsui East Kowloon Hong Kong Tel: (852) 2721-9778 Fax: (852) 2722-1369

#### Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan Tel: (81) 3-3523-3551 Fax: (81) 3-3523-7581

### **Atmel Operations**

Memory 2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

#### Microcontrollers

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

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### Biometrics/Imaging/Hi-Rel MPU/

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